

CALL FOR PAPERS – ISPD 2018

ACM International Symposium on Physical Design

with a tribute to Professor Te C. Hu

<http://www.ispd.cc>

March 25-28, 2018

Monterey, California, USA

Sponsored by ACM SIGDA with Technical Co-sponsorship from IEEE CAS

The International Symposium on Physical Design provides a premier forum to exchange ideas and promote research on critical areas related to the physical design of VLSI systems. All aspects of physical design, including its interactions with architecture, behavioral- and logic-level synthesis, and back-end performance analysis and verification are within the scope of the symposium. Target domains include semi-custom and full-custom ICs, regular fabrics, FPGAs, and systems-on-chip/systems-in-package. Following its twenty-six predecessors, the 2018 symposium will highlight key new directions and leading-edge theoretical and experimental contributions to the field. The ACM Press will publish accepted papers in the Symposium proceedings. ISPD will recognize excellent contributions through a Best Paper Award. Topics of interest include but are not limited to:

Floorplanning and interconnect planning

Partitioning, placement and routing

Physical design for manufacturability and yield

Synthesis optimizations within physical design

Estimation and modeling

Timing and crosstalk issues in physical design

Special structures for clocking and power networks

Physical design for emerging process technologies

Interactions with system and logic level design

Analysis and management of power dissipation

Management of design data and constraints

New physical design methodologies

Physical design for FPGAs

Circuit performance measurements in a PD context

Multithreaded/distributed algorithms for physical design

Hardware security related physical design

IMPORTANT DATES	Title and abstract submission deadline	October 1, 2017
	Full manuscript submission deadline	October 8, 2017
	Acceptance notification	November 18, 2017
	Camera-ready paper due	End of January, 2018

SUBMISSION OF PAPERS

All papers must be submitted electronically via <https://easychair.org/conferences/?conf=ispd2018>. Details will be posted on the website <http://www.ispd.cc>. Potential authors will be required to submit full-length, original, unpublished papers (a maximum of 8 pages in ACM conference format) along with an abstract of at most 200 words and contact author information (name, mailing address, telephone/fax, e-mail). *Previously published papers or papers currently submitted for publication to other conferences/journals will not be considered. If one or more related papers have been previously published or have been concurrently submitted elsewhere for publication, the authors should clearly state the differences between these papers and the current submission. All submitted papers will be under blind reviews, and thus they must not include name(s) or affiliation(s) of the author(s) anywhere in the manuscripts. Failure to comply with these requirements will result in automatic rejection.*

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